

## 1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

|                |              |
|----------------|--------------|
| Part Number :  | CJQ014SN06AL |
| Package Type : | SOP8         |

## 2. MATERIAL ANALYSIS DATA SHEET

| Material      | Composition                     | CAS No.      | % of weight | % of weight |
|---------------|---------------------------------|--------------|-------------|-------------|
| Wafer         | Si                              | 7440-21-3    | 100.000000% | 1.06%       |
| Lead Frame    | Cu                              | 7440-50-8    | 97.692000%  | 51.49%      |
|               | Fe                              | 7439-89-6    | 2.100000%   |             |
|               | P                               | 7723-14-0    | 0.100000%   |             |
|               | Zn                              | 7440-66-6    | 0.100000%   |             |
|               | Pb                              | 7439-92-1    | 0.002000%   |             |
|               | Ag                              | 7440-22-4    | 0.006000%   |             |
| Epoxy         | Silver                          | 7440-22-4    | 79.500000%  | 0.32%       |
|               | epoxy resin                     | 9003-36-5    | 15.000000%  |             |
|               | 1,4-bis(2,3 epoxypropoxy)butane | 2425-79-8    | 4.000000%   |             |
|               | dapsone                         | 80-08-0      | 1.500000%   |             |
| Wire          | Copper                          | 7440-50-8    | 99.995000%  | 0.01%       |
|               | Palladium                       | 7440-05-3    | 0.001000%   |             |
|               | Gold                            | 7440-57-5    | 0.001000%   |             |
|               | Silver                          | 7440-22-4    | 0.001000%   |             |
|               | Copper                          | 7440-50-8    | 99.997800%  |             |
|               | Iron                            | 7439-89-6    | 0.000200%   |             |
|               | Silver                          | 7440-22-4    | 0.001000%   |             |
|               | Other                           | -            | 0.001000%   |             |
| Mold Compound | Epoxy resin A                   | Trade Secret | 2.000000%   | 43.72%      |
|               | Epoxy resin B                   | Trade Secret | 3.000000%   |             |
|               | Epoxy resin C                   | Trade Secret | 2.000000%   |             |
|               | Phenol Resin                    | Trade Secret | 4.000000%   |             |
|               | catalyst                        | Trade Secret | 0.500000%   |             |
|               | Carbon black                    | 1333-86-4    | 0.200000%   |             |
|               | Silica(Amorphous) A             | 60676-86-0   | 81.300000%  |             |
|               | Silica(Amorphous) A             | 7631-86-9    | 7.000000%   |             |
| Plating       | Sn                              | 7440-31-5    | 99.900000%  | 3.40%       |
|               | Others                          | -            | 0.100000%   |             |

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.